

Light Avenue Premium Edition LED series is designed for high performance consumer applications. Remarkable light extraction is reached by a particular top emitting design with vertical chip structure. As this die can be driven at very high currents compared to the chip size, an outstanding cost vs. performance ratio can be obtained.



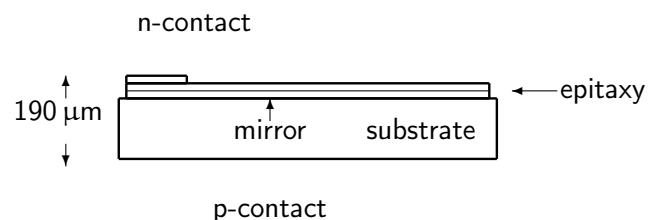
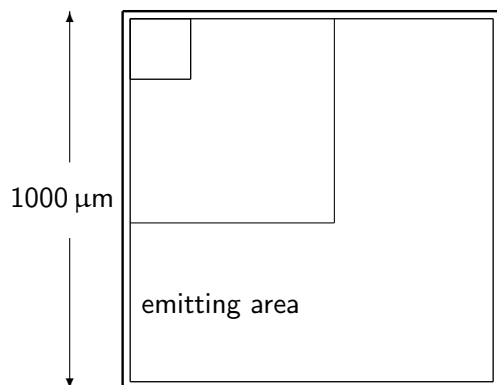
Features

- Highest brightness InGaN chip
- Top emitting device
- Lambertian radiation
- Optimized for SMT applications
- Chip with 2 contact rings
- Grouping: radiant power, wavelength

Applications

- Solid state lighting
- LCD backlighting
- Lamps
- Displays
- Light indicators

Delineation



Mechanical characteristics

DESCRIPTION	MINIMUM	TYPICAL ¹	MAXIMUM
Chip size (μm)	950	1000	1050
Chip height (μm)	170	190	210
Bond pad diameter (μm)	160	180	200
Top contact	Cathode (n), gold		
Bottom contact	Anode (p), gold alloy		
Die attach	Epoxy bonding		

Electro-optical characteristics ($T_A = 25^\circ\text{C}$)²

PARAMETER	SYMBOL	CONDITION	MIN.	TYP. ¹	MAX.	UNIT
Forward voltage	V_F	$I_F = 350\text{ mA}$	2.70		3.80	V
Reverse voltage	V_R	$I_R = 10\ \mu\text{A}$	5.0			V
Dominant wavelength	λ_{dom}	$I_F = 350\text{ mA}$	455		467.5	nm
Radiant power	Φ_e	$I_F = 350\text{ mA}$	160	400		mW

Maximum ratings ($T_A = 25^\circ\text{C}$)³

PARAMETER	SYMBOL	VALUE	UNIT
Operating temperature range	T_{op}	-40...+85	°C
Forward current	I_F	700	mA
LED junction temperature	T_j	125	°C

Binning ($I_F = 350\text{ mA}$)⁴

		WAVELENGTH (NM)			
		455-460	457.5-462.5	460-465	462.5-467.5
Radiant power (mW)	> 160	Y29	YM29	Z29	ZM29
	> 200	Y30	YM30	Z30	ZM30
	> 250	Y31	YM31	Z31	ZM31
	> 320	Y32	YM32	Z32	ZM32
	> 400	Y33	YM33	Z33	ZM33

Notes:

- The usage of LEDs in life-support devices or systems has to be expressly and written authorized by the supplier!
- Dice are sensitive to ESD.
- Dice are shipped on blue foil with or without frame and have therefore to be stored between 15 and 30°C and below 60% relative humidity.
- Lead free product - RoHS compliant.
- The information in this document is subject to change without notice and describes the die generally. It shall not be considered as assured characteristics or detailed specification.

- The quality level of the final visual inspection shall comply to an AQL of 1.0 (according to MIL-STD-105E, level II), if the customer performs an incoming visual inspection of a shipment.
- All chips are checked according to the "Failure Catalog of Light Avenue dice" dated 2009-11-14. If this document is not familiar to you, please request it at your next sales office.

¹Typical (Typ) data are defined as long-term production mean values. These values are not specified and only given for information.

²Measurements are done with an accuracy of $\pm 15\%$. Correlation to customer's equipment and products is required.

³Maximum ratings are package dependent and may differ between packages. The forward current is not limited by the die but by the effect of the LED junction temperature on the package. If you need more information on pulsed operation, please contact your next sales office about possible driving conditions. If not otherwise specified the maximum pulse current may not exceed the maximum current in continuous mode.

⁴There may be more than one bin on one single foil. Single bins cannot be ordered.